

Micron Technology, Inc. Quality & Reliability Assurance Dept Mail Stop 502 8000 S. Federal Way P.O. Box 6 Boise, Idaho 83707-0006

**RE: RoHS Certification** 

Micron Technology, Inc. certifies that our Pb-free die/wafer and component level products meet the requirements of the current DIRECTIVE 2011/65/EU and 2015/863/EU, a.k.a. Restriction of Hazardous Substances (RoHS) Directive (Recast).

Micron's Pb-free products mentioned above contain less than the following amounts of the RoHS banned substances:

- Less than 0.1% Lead Pb
- Less than 0.1 % Mercury Hg
- Less than 0.01 % Cadmium Cd
- Less than 0.1 % Hexavalent Chromium Cr(VI)
- Less than 0.1 % Polybrominated Biphenyls PBB
- Less than 0.1 % Polybrominated Diphenyl Ethers PBDE
- Less than 0.1 % Decabromodiphenyl Ether DecaBDE
- Less than 0.1 % Bis(2 ethylhexyl) phthalate / Di 2 ethylhexyl phthalate DEHP
- Less than 0.1 % Butyl benzyl phthalate -BBP
- Less than 0.1 % Dibutylphthalate DBP
- Less than 0.1 % Diisobutyl phthalate DIBP

Please note that our module level products do contain electronic ceramic passive parts that may use lead or lead-oxides which are exempt from Directive 2011/65/EU (see Article 4, Annex III of the Annex thereto).

The information provided above, applies to all Micron products, including part number CT2000BX500SSD1.

Further questions should be addressed to your local Micron sales representative.

Micron Technology, Inc. Global Supply Chain Compliance Department